Abstracts

Low-Cost Package Technology for Advanced MMIC Applications

S. Chai, R. Kirschman, S. Ludvik, J. Bedinger, L. Harmon, R. Burkholder, M. Fallica, S. Tarbox, M. Doherty, J. Oenning and I. Clark. "Low-Cost Package Technology for Advanced MMIC Applications." 1990 MTT-S International Microwave Symposium Digest 90.1 (1990 Vol. I [MWSYM]): 625-628.

Availability of MMICs along with expanded applications for microwave components, places increasing demands on performance and cost of package technology. We report progress in meeting these demands with metal-injection molding (MIM) of metal-matrix composites for advanced microwave packaging technology. We present our experiences in developing this technology, including dimensional control, plating, hermeticity, and cost. Electrical performance of packaged multi-chip amplifiers operating 2-20 GHz is also described.

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